

Description

The Si2304BDS-T1-GE3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =4A

 $R_{DS(ON)}$ < 38m Ω @ V_{GS}=10V

Application

Battery protection

Load switch Uninterruptible power supply

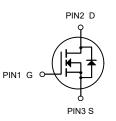
Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------------|--------|------------|----------|
| Si2304BDS-T1-GE3 | SOT-23 | HXY MOSFET | 3000 |

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Symbol | Parameter | Limit | Unit | |
|-----------------|---|-------|------|--|
| VDS | Drain-Source Voltage | 30 | V | |
| V _{GS} | Gate-Source Voltage | ±20 | V | |
| ID | Drain Current-Continuous | 4 | А | |
| Ідм | Drain Current-Pulsed (Note 1) | 16.4 | А | |
| PD | Maximum Power Dissipation | 1 | W | |
| Tj,Tstg | Operating Junction and Storage Temperature Range -55 To 150 | | °C | |
| Reja | Thermal Resistance, Junction-to-Ambient (Note 2) | 125 | °C/W | |





N-Channel MOSFET

N-Channel Enhancement Mode MOSFET



| Symbol | Parameter | Test Condition | Min. | Тур. | Max. | Units |
|----------------------|---|--|------|------|------|-------|
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250µA | 30 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =30V, V _{GS} =0V, | - | - | 1.0 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±20V | - | - | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250µA | 1.0 | 1.5 | 2.5 | V |
| RDS(on) | Static Drain-Source on-Resistance | V _{GS} =10V, I _D =4A | - | 29 | 38 | mΩ |
| | | V _{GS} =4.5V, I _D =3A | - | 45 | 65 | |
| Ciss | Input Capacitance | | - | 233 | - | pF |
| Coss | Output Capacitance | V_{DS} =15V, V_{GS} =0V, | - | 44 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | f=1.0MHz | - | 33 | - | pF |
| Qg | Total Gate Charge | - V _{DS} =15V, I _D =2A, | - | 3 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 0.5 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | V _{GS} =10V | - | 0.8 | - | nC |
| t _{d(on)} | Turn-on Delay Time | - V _{DS} =15V, - I _D =4A, R _{GEN} =3Ω, | - | 4 | - | ns |
| tr | Turn-on Rise Time | | - | 2.1 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 15 | - | ns |
| t _f | Turn-off Fall Time | V _{GS} =10V | - | 3.2 | - | ns |
| ls | Maximum Continuous Drain to Source Diode Forward Current | | - | - | 4 | А |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | 16 | Α |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S =4A | - | - | 1.2 | V |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Si2304BDS-T1-GE3 N-Channel Enhancement Mode MOSFET

Typical Characteristics

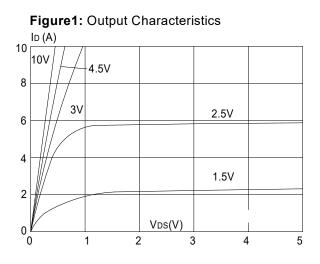
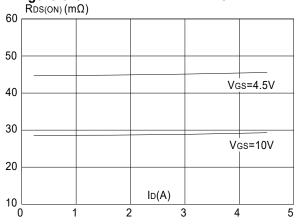
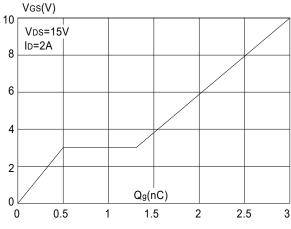
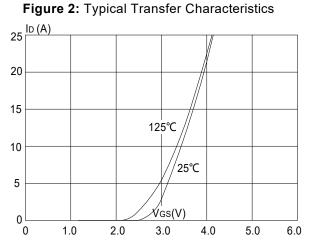


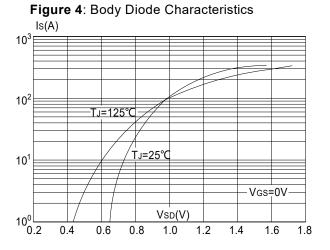
Figure 3:On-resistance vs. Drain Current











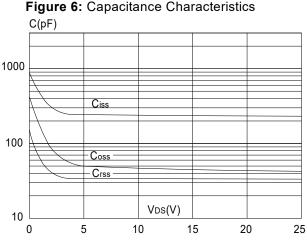


Figure 6: Capacitance Characteristics



Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

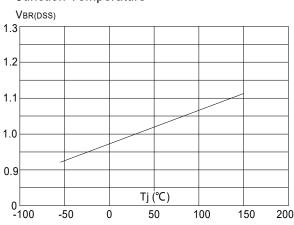


Figure 9: Maximum Safe Operating Area

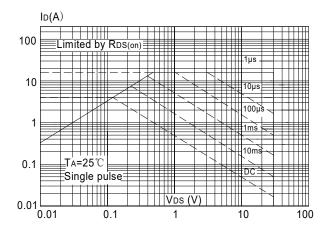


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

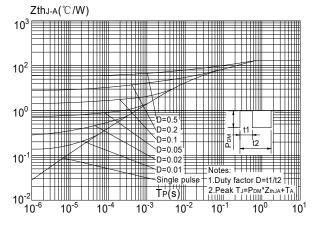


Figure 8: Normalized on Resistance vs. Junction Temperature

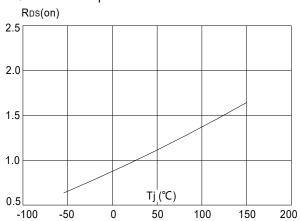
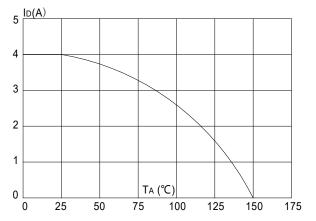
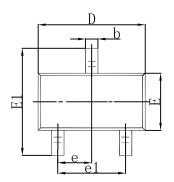


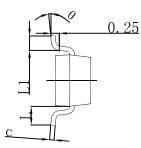
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

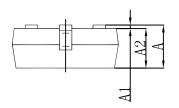




SOT-23 Package Outline Dimensions

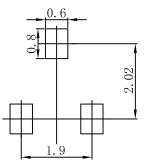






| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| Α | 0.900 | 1.150 | 0.035 | 0.045 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 2.800 | 3.000 | 0.110 | 0.118 | |
| E | 1.200 | 1.400 | 0.047 | 0.055 | |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 | |
| е | 0.950 TYP | | 0.037 TYP | | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.550 REF | | 0.022 REF | | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 | |
| θ | 0° | 8° | 0° | 8° | |

SOT-23 Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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